NOTES

1. MATERIALS:
   - LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
   - BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
2. FINISH:
   - LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICRONCHES (2.5um - 7.6um) THICK.
   - GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONCHES (1um - 2um) THICK).
   - BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220.